

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A method for establishing ~~an~~a temporary electrical contact with at least one semiconductor device, comprising:
establishing ~~an~~a temporary electrical contact between a first member of an electrical connector and a contact that is in electrical communication with the at least one semiconductor device;~~and~~
magnetically drawing at least one of the first member and the contact toward the other of the first member and the contact; and
permitting an electrical current to flow from at least one of the electrical connector and the contact to the other of the contact and the electrical connector as the temporary electrical contact is maintained.

2. (Previously Presented) The method of claim 1, wherein magnetically drawing is effected in a direction substantially normal to a plane of the contact.

3. (Previously Presented) The method of claim 1, wherein magnetically drawing is effected in a direction substantially normal to a plane of a substrate upon which the contact is carried.

4. (Previously Presented) The method of claim 1, wherein magnetically drawing is effected by positioning a second member of the electrical connector opposite the first member.

5. (Previously Presented) The method of claim 4, wherein magnetically drawing is effected by magnetically attracting at least one of the first member and the second member toward at least the other of the first member and the second member.

6. (Previously Presented) The method of claim 4, wherein magnetically drawing comprises securing the first and second members to a substrate upon which the contact is carried.

7. (Previously Presented) The method of claim 1, wherein magnetically drawing comprises magnetically securing the first member to the contact.

8. (Currently Amended) A method for stress testing a plurality of semiconductor devices carried upon a common substrate and in communication with common ground and power contacts, comprising:

establishing a temporary electrical contact between a first member of an electrical connector and at least one contact of the ground contact and the power contact; ~~and~~

magnetically drawing at least one of the first member and the at least one contact toward the other of the first member and the at least one contact to maintain the temporary electrical contact; and

permitting an electrical current to flow from at least one of the electrical connector and the contact to the other of the contact and the electrical connector as the temporary electrical contact is maintained.

9. (Previously Presented) The method of claim 8, wherein magnetically drawing is effected in a direction substantially normal to a plane of the common substrate.

10. (Withdrawn and currently amended) The method of claim 8, wherein ~~said~~ the magnetically drawing nonrigidly biases ~~said~~ the first member against ~~said~~ the at least one contact.

11. (Previously Presented) The method of claim 8, wherein magnetically drawing comprises positioning a second member of the electrical connector opposite the substrate from the first member.

12. (Previously Presented) The method of claim 11, wherein at least one of the first member and the second member is drawn toward at least the other of the first member and the second member.

13. (Previously Presented) The method of claim 12, wherein magnetically drawing comprises magnetically attracting at least one of the first member and the second member toward at least the other of the first member and the second member.

14. (Previously Presented) The method of claim 8, wherein magnetically drawing comprises magnetically securing the first member to the at least one contact.

15. (Previously Presented) The method of claim 8, wherein magnetically drawing comprises securing at least the first member in position relative to the substrate.

16. (Previously Presented) The method of claim 8, further comprising:
electrically connecting another first member of another electrical connector to another of the ground contact and the power contact; and
magnetically drawing the another first member toward the another contact.

17. (Previously Presented) The method of claim 16, further comprising:
applying a substantially constant amount of current to each semiconductor device of the plurality of semiconductor devices through the first member and the another first member.

18. (Original) The method of claim 17, further comprising:
heating each of the plurality of semiconductor devices.

19. (Previously Presented) The method of claim 18, wherein heating comprises cycling a temperature of each of the plurality of semiconductor devices.

20. (Previously Presented) The method of claim 18, wherein heating comprises varying a temperature of each of the plurality of semiconductor devices.